

SURFACE MOUNT LOW LEAKAGE SILICON DIODE



Central Semiconductor Corp.

www.centralsemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMHD3595 is a silicon diode, manufactured by the epitaxial planar process, epoxy molded in a surface mount package, designed for high conductance applications requiring low leakage.

MARKING CODE: C95

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V _{RRM}	150	V
Peak Working Reverse Voltage	VRWM	125	V
Average Forward Current	IO	150	mA
Continuous Forward Current	١ _F	225	mA
Recurrent Peak Forward Current	i _f	600	mA
Peak Forward Surge Current, tp=1.0s	IFSM	500	mA
Peak Forward Surge Current, tp=1.0µs	IFSM	4.0	А
Power Dissipation	PD	400	mW
Operating and Storage Junction Temperature	т _Ј , т _{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	312.5	°C/W

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

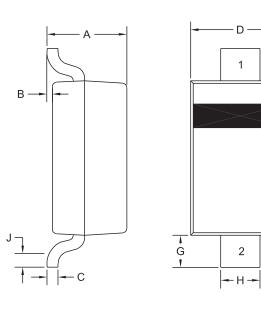
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I _R	V _R =125V		1.0	nA
I _R	V _R =125V, T _A =125°C		2.0	μA
I _R	V _R =125V, T _A =150°C		5.0	μΑ
I _R	V _R =30V, T _A =125°C		300	nA
BVR	I _R =100μΑ	150		V
V _F	I _F =1.0mA	0.54	0.69	V
VF	I _F =5.0mA	0.62	0.77	V
VF	I _F =10mA	0.65	0.80	V
V _F	I _F =50mA	0.75	0.88	V
VF	I _F =100mA	0.79	0.92	V
VF	I _F =200mA	0.83	1.00	V
СЈ	V _R =0, f=1.0MHz		8.0	pF
t _{rr}	V_R =3.5V, I _F =10mA, R _L =1.0k Ω		3.0	μs

R6 (17-June 2019)



CMHD3595

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LEAD CODE

MARKING CODE: C95

1) Cathode

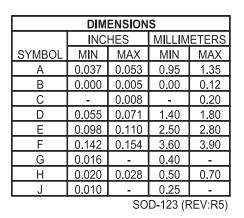
2) Anode

SOD-123 CASE - MECHANICAL OUTLINE

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OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

ss your design challenges.

· Custom product packing

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

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